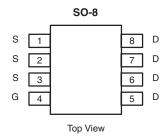




N-Channel 25-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)		
25	0.0105 at V _{GS} = 10 V	16.2	12.4 nC		
	0.0125 at V _{GS} = 4.5 V	13	12.4110		



Ordering Information: Si4668DY-T1-E3 (Lead (Pb)-free)

Si4668DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

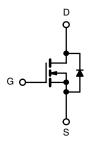
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Synchronous Buck
 - High Side



N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	25	V	
Gate-Source Voltage		V _{GS}	± 16		
	T _C = 25 °C		16.2		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	L .	13		
Continuous Diain Current (1) = 150 °C)	T _A = 25 °C	I _D	11.5 ^{b, c}		
	T _A = 70 °C		9.2 ^{b, c}		
Pulsed Drain Current		I _{DM}	60	A	
Continuous Source-Drain Diode Current	T _C = 25 °C		4.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	l _s	2.2 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	15		
Avalanche Energy L = 0.1 mH		E _{AS}	11.25	mJ	
	T _C = 25 °C		5		
Maximum Dawar Dissination	T _C = 70 °C	P _D	3.2	w	
Maximum Power Dissipation	T _A = 25 °C	' D	2.5 ^{b, c}	VV	
	T _A = 70 °C		1.6 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	43	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	19	25		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 95 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				•		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	25			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		25		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.7		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	8.0		2.6	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА
		$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α
Drain-Source On-State Resistance ^a	Б	V _{GS} = 10 V, I _D = 15 A		0.0085	0.0105	Ω
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.010	0.0125	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		58		S
Dynamic ^b						
Input Capacitance	C _{iss}			1654		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		245		
Reverse Transfer Capacitance	C _{rss}			106		
Total Gate Charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A		27.5	42	nC
				12.4	19	
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		4		
Gate-Drain Charge	Q _{gd}			3.3		
Gate Resistance	R_g	f = 1 MHz		0.6	1.2	Ω
Turn-On Delay Time	t _{d(on)}			21	40	ns
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		12	24	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		73	120	
Fall Time	t _f			18	35	
Turn-On Delay Time	t _{d(on)}			10	20	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		11	22	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		23	45	
Fall Time	t _f			8	16	
Drain-Source Body Diode Characterist	cs			•		
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			4.5	Δ
Pulse Diode Forward Current ^a	I _{SM}				60	Α
Body Diode Voltage	V_{SD}	I _S = 3 A		0.77	1.1	٧
Body Diode Reverse Recovery Time	t _{rr}			22	40	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		15	30	nC
Reverse Recovery Fall Time	ta			12		
Reverse Recovery Rise Time	t _b			10		ns

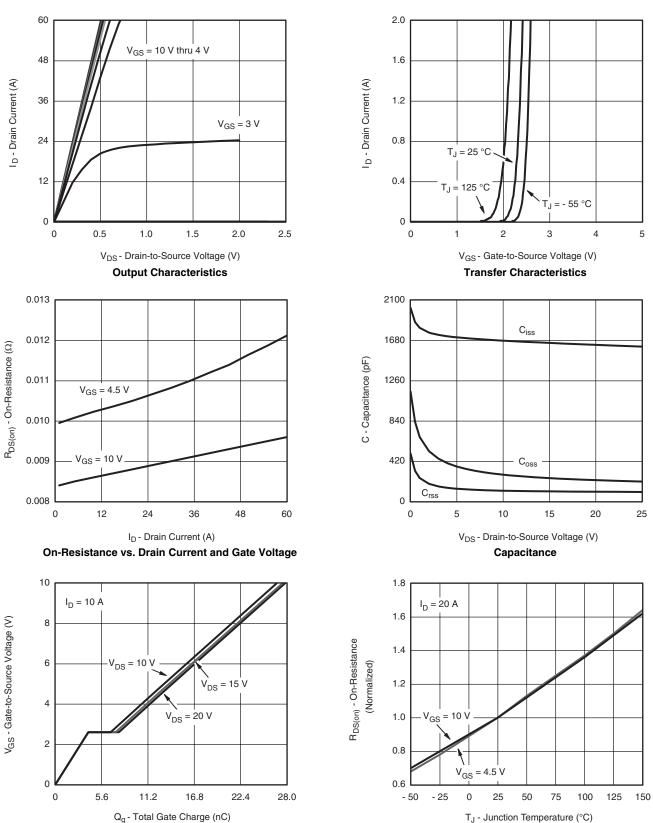
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



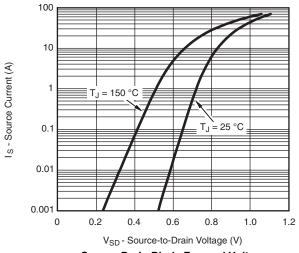
Gate Charge

On-Resistance vs. Junction Temperature

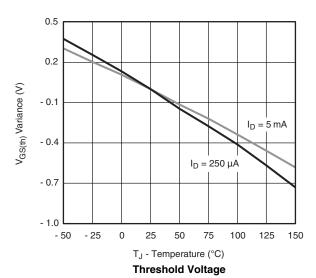
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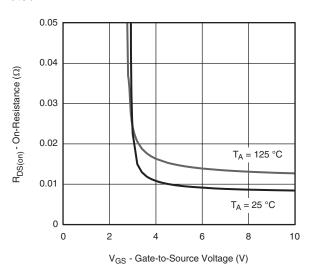
VISHAY

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

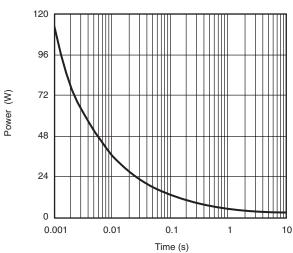


Source-Drain Diode Forward Voltage

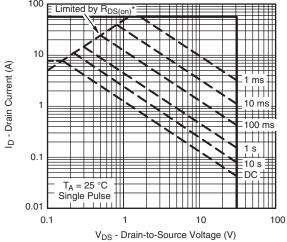




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

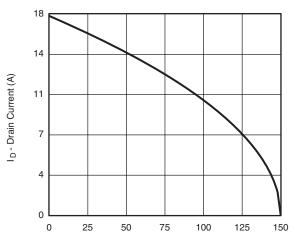


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

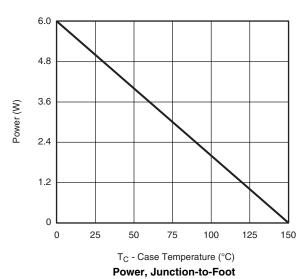


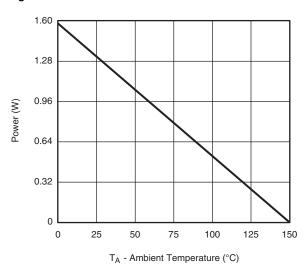
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 $T_{\mbox{\scriptsize C}}$ - Case Temperature (°C)

Current Derating*





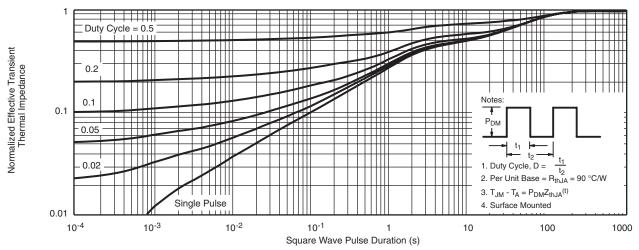
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

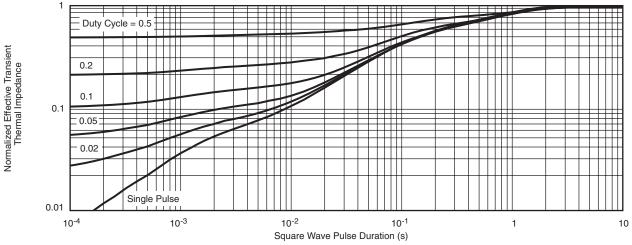
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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